

50MHz-6000MHz, Cascadable Amplifier

Product Overview

The SBB5089Z is a high performance InGaP HBT MMIC amplifier utilizing a Darlington configuration with an active bias circuitry. The active bias circuitry provides stable current over temperature and process variations. The SBB5089Z designed to run directly from a 5V supply, does not require a dropping resistor as compared to typical Darlington amplifiers. The SBB5089Z is a high linearity gain block for applications that require small in size with minimal number of external components. It is internally matched to 50 Ω at input and output.

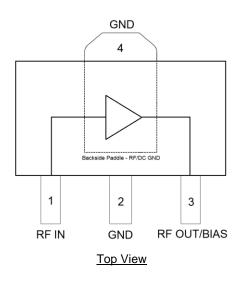


3 Pin SOT-89 Package

Key Features

- 50 MHz 6000 MHz
- ±1.1 dB Wideband Flat Gain up to 4000 MHz
- +20.4 dBm P1dB at 1950 MHz
- +5 V Single Fixed Supply
- 1000V, HBM Class 1C Robust ESD
- · Patented Thermal Design and Bias Circuitry
- Low Thermal Resistance

Functional Block Diagram



Applications

- PA Driver Amplifier
- · Cellular, PCS, GSM, UMTS
- Wideband Instrumentation
- Wireless Data, Satellite Terminals

Ordering Information

Part No.	Description		
SBB5089Z	1,000 pieces on a 7" reel (standard)		
SBB5089ZPCK1	500-3500 MHz Evaluation Board with a 5-piece sample bag		



50MHz-6000MHz, Cascadable Amplifier

Absolute Maximum Ratings

Parameter	Rating
Storage Temperature	−55 to +150 °C
RF Input Power, CW, 50 Ω, T=25 °C	+24 dBm
Device Voltage (Vc)	+5.5 V
Device Current (I _C)	100 mA
Dissipated Power (PDISS)	0.55 W
Junction Temperature (T _J)	+150 °C

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability.

Recommended Operating Conditions

Parameter	Min	Тур	Max	Units
Device Voltage (V _C)	+4.75	+5	+5.25	V
T _{CASE}	-55		+105	°C

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

Electrical Specifications

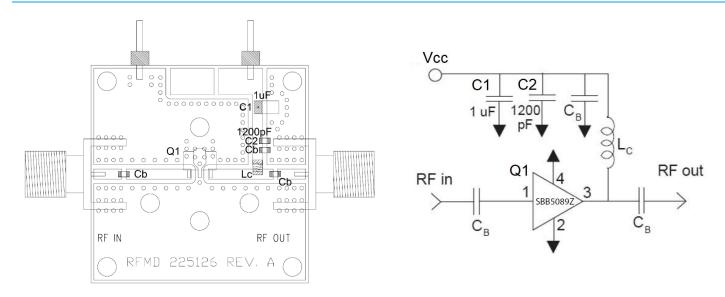
Parameter	Conditions (1)	Min	Тур	Max	Units
Operational Frequency Range		50		6000	MHz
Gain, Small Signal	850 MHz	19.0	20.5	22.0	dB
	1950 MHz	18.3	19.0	21.5	dB
	6000 MHz	14.5	15.5	17.5	dB
Input Return Loss	1950 MHz	10	13		dB
Output Return Loss		10	14		dB
Output P1dB	850 MHz		20.5		dBm
	1950 MHz	19.0	20.0		dBm
Output IP3 (2)	850 MHz		38.5		dBm
	1950 MHz	33.0	35.0		dBm
Bandwidth	Minimum 10 dB typical return loss		3000		MHz
Reverse Isolation	1950 MHz		23.3		dB
Noise Figure			3.9	4.9	dB
Device Operating Current, I _C	Pin 3	60	75	92	mA
Thermal Resistance, θ _{jc}	Junction to case		69.9		°C/W

^{1.} Test conditions unless otherwise noted: V_C = +5.0 V, I_C = 75 mA, Temp = +25 °C, 50 Ω test system, Tested with Bias Tees

^{2.} $P_{OUT} = 0$ dBm/tone, $\Delta f = 1$ MHz



500 - 3500 MHz Evaluation Board - SBB5089ZPCK1



Bill of Material - SBB5089ZPCK1

Reference Des.	Value	Description	Manuf.	Part Number
PCB	-	Printed Circuit Board	Qorvo	
Q1	-	SBB5089Z Amplifier, SOT-89 pkg.	Qorvo	SBB5089Z
C1	1 µF	CAP, 1 µF, 20%, 20V, TANT, 1206	various	
C2	1200 pF	CAP, 1200 pF, 10%, 50V, X7R, 0603	various	
Св	68 pF	CAP, 68 pF, 5%, 50V. NPO/C0G, 0603	various	
Lc	82 nH	IND, 82 nH, 5%, W/W, 0805	Coilcraft	0805CS-330XJLB

Note for < 500 MHz: C_B 1.0 μF , 10%, 160, X7R, 0603; L_C 330 nH, 5%, 0805

Typical Performance - SBB5089ZPCK1

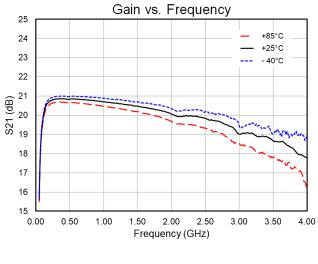
Parameter (1)	Typical Value							Units		
Frequency	50	100	200	500	850	1950	2500	3500	4000	MHz
Gain, Small Signal	21.1	20.9	20.8	20.8	20.8	20.1	19.8	18.7	17.8	dB
Input Return Loss	11.3	17.4	24.3	27.2	22.7	14.6	12.9	10.6	11.6	dB
Output Return Loss	15.9	21.7	30.4	31.8	21.5	13.5	12.0	13.5	27.5	dB
Reverse Isolation	17.4	17.5	17.5	22.7	22.8	23.4	23.7	24.7	25.7	dB
Output P1dB	19.4	19.7	20.0	20.5	20.4	20.4	19.4	16.9	14.7	dBm
OIP3 (2)	36.0	37.8	37.5	38.6	39.2	34.9	32.8	29.4	26.8	dBm
Noise Figure	4.4	4.4	4.3	3.8	3.8	4.1	4.1	4.3	4.6	dB

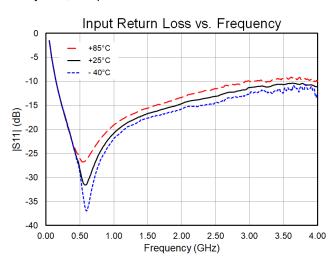
- 1. Test conditions unless otherwise noted: V_{CC} = +5V, I_{C} = 75 mA , 50 Ω test system, Temp.=+25 °C
- 2. Pout= 0 dBm/tone, Δf=1 MHz

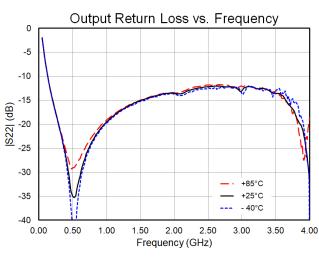


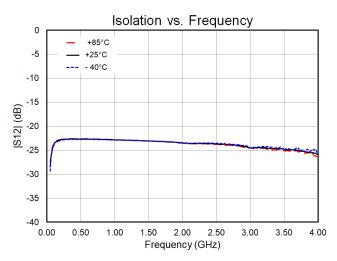
Performance Plots - SBB5089ZPCK1

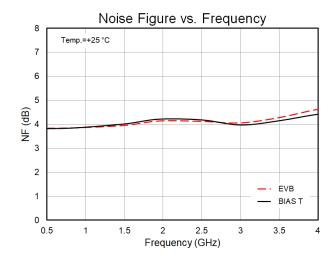
Test conditions unless otherwise noted: V_{CC} = +5V, I_C = 75 mA, 50 Ω test system, Temp.=+25 °C

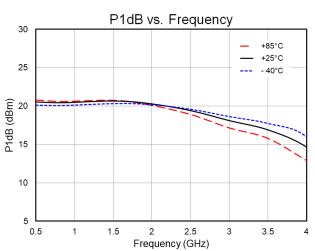








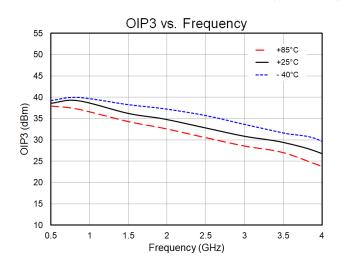


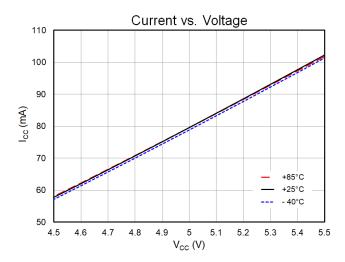


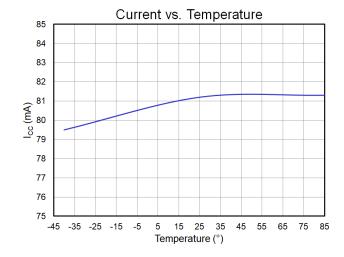


Performance Plots - SBB5089ZPCK1 (continued)

Test conditions unless otherwise noted: $V_{CC} = +5V$, $I_C = 75$ mA, 50Ω test system, Temp.=+25 °C



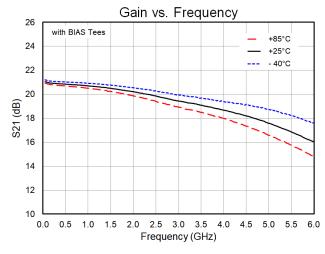


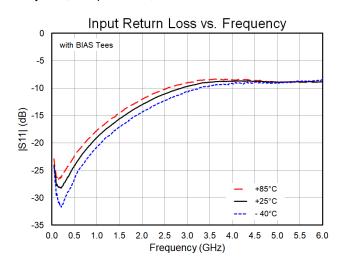


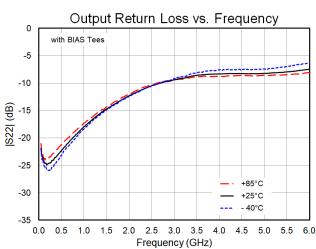


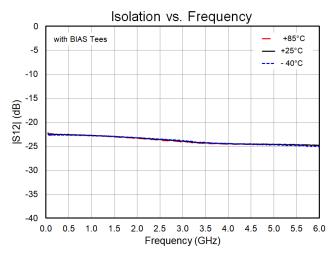
Performance Plots - with BIAS Tees

Test conditions unless otherwise noted: V_C = +5V, I_C = 75 mA, 50 Ω test system, Temp.=+25 °C, with BIAS Tees



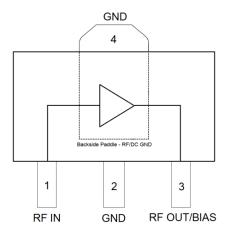








Pad Configuration and Description



Top View

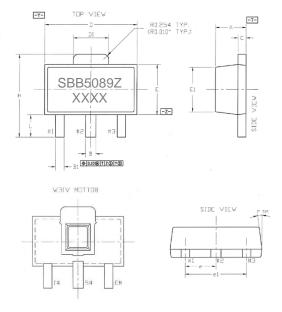
Pad No.	Label	Description
1	RF IN	RF input. External DC Block capacitor required.
3	RF OUT/BIAS	RF output and DC Supply input. External DC Block capacitor and bias voltage required.
2, 4 Backside Paddle	GND	RF/DC ground. Use recommended via hole pattern to minimize inductance and thermal resistance. See PCB Mounting Pattern for suggested footprint.





Package Marking and Dimensions Outline A

Package Marking: Product ID: SBB5089Z Trace Code: XXXX



S			Com	mon		
MB	DIMENSI	ONS MILL	IMETER	TER DIMENSIONS INC		
	MIN.	NDM.	MAX.	MIN.	NOM.	MAX.
Α	1.40	1.50	1.60	0.055	0.059	0.063
В	0.44	0.50	0.56	0.017	0.020	0.022
B1	0.36	0.42	0.48	0.014	0.017	0.019
C	0.35	0.40	0.44	0.014	0.016	0,017
D	4.40	4.50	4.60	0.173	0.177	0.181
D1	1.62	1.73	1.83	0.064	0.068	0.072
E	2.30	2.50	2.60	0.091	0.098	0.102
E1	2.13	2.20	2.29	0.084	0.087	0.090
6	1.	50 BSC		0.0	59 BS	Ċ.
e1	3.00 BSC.			0.	118 BSC	3.
Н	3.95	4.10	4.25	0.156	0.161	0.167
L	0.90	1.10	1.20	0.035	0.043	0.047

NOTES :

- DIMENSIONING & TOLERANCING PER ANSILY14.5M-1982
 CONTROLLING DIMENSION: MILLIMETER CONVERTED INCH ARE NOT NECESSARILY EXACT.
 DIMENSION B1, 2 PLACES.

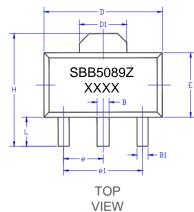
Notes:

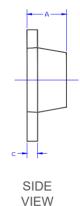
- 1. All dimensions are in millimeters. Angles are in degrees.
- 2. Dimension and tolerance formats conform to ASME Y14.4M-1994.
- 3. The terminal #1 identifier and terminal numbering conform to JESD 95-1 SPP-012.
- 4. Trace code up to 4 characters to be assigned by sub-contractor.
- 5. Contact plating: NiPdAu
- 6. Either package dimensions outline A or B may be supplied.
- 7. This package outline is shipped as MSL5A.

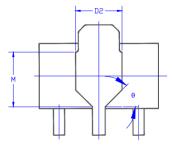
Package Marking and Dimensions Outline B

Package Marking

Product ID: SBB5089Z Trace Code: XXXX







BOTTOM

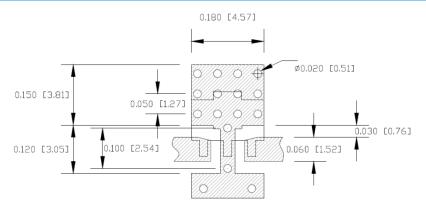
VIEW

Symbol	Dimensions I	n Millimeters		
Symbol	Min.	Max.		
Α	1.400	1.600		
В	0.400	0.580		
B1	0.320	0.520		
С	0.350	0.440		
D	4.400	4.600		
D1	1.550 REF.			
D2	1.600	REF.		
E	2.300	2.600		
е	1.500	TYP.		
e1	3.000	TYP.		
н	3.940	4.250		
L	0.900	1.200		
M	1.900REF.			

- 1. All dimensions are in millimeters. Angles are in degrees.
- 2. Dimension and tolerance formats conform to ASME Y14.4M-1994.
- 3. The terminal #1 identifier and terminal numbering conform to JESD 95-1 SPP-012.
- 4. Trace code up to 4 characters to be assigned by sub-contractor.
- 5. Contact plating: Matte Sn
- 6. Either package dimensions outline A or B may be supplied.
- 7. This package outline is shipped as MSL3.



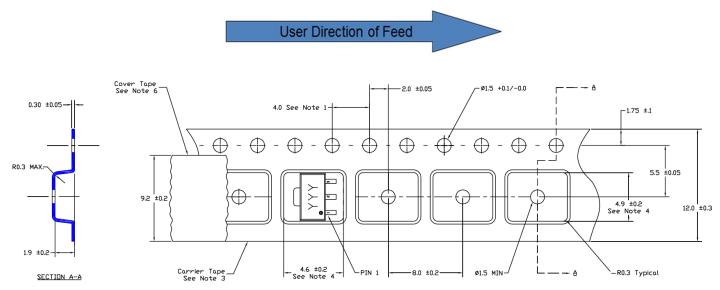
PCB Mounting Pattern



- 1. All dimensions are in millimeters. Angles are in degrees.
- 2. Use 1 oz. copper minimum for top and bottom layer metal.
- 3. Via holes are required under the backside paddle of this device for proper RF/DC grounding and thermal dissipation.
- 4. Do not remove or minimize via hole structure in the PCB. Thermal and RF grounding is critical.
- 5. We recommend a 0.35mm (#80/.0135") diameter bit for drilling via holes and a final plated thru diameter of 0.25 mm (0.01").
- 6. Ensure good package backside paddle solder attach for reliable operation and best electrical performance.



Tape and Reel Information – Carrier and Cover Tape Dimensions



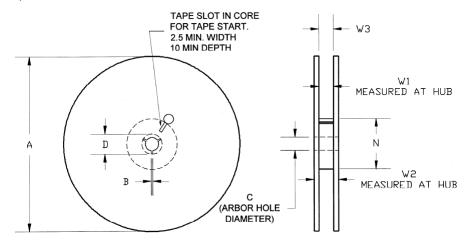
- 1. 10 sprocket hole pitch cumulative tolerance
 2. Camber not to exceed Imm in 100mm
 3. Material: Black Conductive Polystyrene
 4. Measured on a plane 0.3mm above the bottom of the pocket.
 5. Measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
 6. Material: Antistatic Polyester Film

Feature	Measure	Symbol	Size (in)	Size (mm)
	Length	A0	0.181	4.60
Covity	Width	B0	0.193	4.90
Cavity	Depth	K0	0.075	1.90
	Pitch	P1	0.315	8.00
Centerline Distance	Cavity to Perforation - Length Direction	P2	0.079	2.00
Centenine Distance	Cavity to Perforation - Width Direction	F	0.217	5.50
Cover Tape Width		С	0.362	9.20
Carrier Tape	Width	W	0.472	12.0



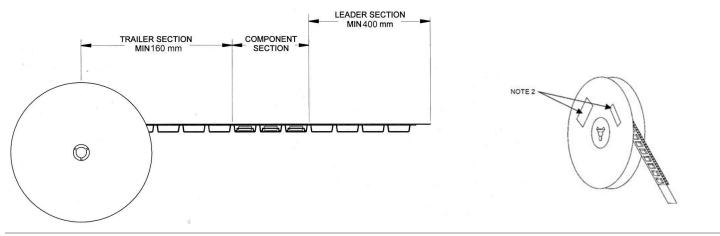
Tape and Reel Information - Reel Dimensions

Standard T/R size = 1,000 pieces on a 7" reel.



Feature	Measure	Symbol	Size (in)	Size (mm)
	Diameter	Α	6.969	177.0
Flange	Thickness	W2	0.717	18.2
	Space Between Flange	W1	0.504	12.8
	Outer Diameter	N	2.283	58.0
Llub	Arbor Hole Diameter	С	0.512	13.0
Hub Key Slit \	Key Slit Width	В	0.079	2.0
	Key Slit Diameter	D	0.787	20.0

Tape and Reel Information - Tape Length and Label Placement



- 1. Empty part cavities at the trailing and leading ends are sealed with cover tape. See EIA 481-1-A.
- 2. Labels are placed on the flange opposite the sprockets in the carrier tape.



Handling Precautions

Parameter	Rating	Standard
ESD – Human Body Model (HBM)	Class 1C	ESDA/JEDEC JS-001-2012
MSL – Moisture Sensitivity Level	See Package Dimensions Outline	IPC/JEDEC J-STD-020



Caution! ESD-Sensitive Device

Solderability

Compatible with the latest version of J-STD-020, lead-free (260°C max. reflow temp.) soldering processes. Solder profiles available upon request.

RoHS Compliance

This part is compliant with 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive 2015/863/EU.

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C₁₅H₁₂Br₄O₂) Free
- PFOS Free
- SVHC Free

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

Web: <u>www.qorvo.com</u>
Tel: 1-844-890-8163

Email: customer.support@gorvo.com

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